

Amendment to the Abstract:

The Abstract has been amended. A revised Abstract is attached.

ABSTRACT-OF-THE-DISCLOSURE

In ~~mounting order to mount an~~ electronic component ~~for mounting~~, a connection terminal (5a) of ~~an~~ the electronic component (5) ~~by bonding~~ is bonded to electrodes (2) of a substrate (1) ~~by~~. This is done by using solder paste (4) ~~mixing~~ which mixes solder particles in a thermosetting adhesive, ~~the~~. The solder paste (4) is supplied to the electrodes (2) and a recess (3) ~~as adhesion reinforcing portion provided in other portion, and solder~~. Solder print parts (4A, 4B) are formed, ~~and the~~. The electronic component (5) is mounted, and the connection terminal (5a) and the main body (5b) of the electronic component (5) are adhered to the solder print parts (4A, 4B), ~~and~~ and are heated in this state by reflow. As a result, the connection terminal (5a) and the electrodes (2) are bonded by a solder junction (6a), ~~and by the adhesive component of the solder print part (4B), second resin reinforced part (7b) is formed for fixing the main body (5b) and substrate (1).~~

Respectfully submitted,

Lawrence E. Ashery, Reg. No. 34,515
Attorney for Applicants

LEA/dmw

Attachment: Abstract

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P.O. Box 980
Valley Forge, PA 19482
(610) 407-0700

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Amanda Kelly

55585

ABSTRACT

In order to mount an electronic component, a connection terminal of the electronic component is bonded to electrodes of a substrate. This is done by using solder paste which mixes solder particles in a thermosetting adhesive. The solder paste is supplied to the electrodes and a recess . Solder print parts are formed. The electronic component is mounted and the connection terminal and the main body of the electronic component are adhered to the solder print parts, and are heated in this state by reflow. As a result, the connection terminal and the electrodes are bonded by a solder junction.